


## Full Material Declaration for attached parts list

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	<p><b>Diotec Semiconductor AG</b>  DUNS number: 330866844  -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany  Declarations authorised by  Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 02 January 2014 [Approved: 19 December 2024 08:16 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.14%	Silicon	7440-21-3	100%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	8.5%
Die attach	Other nonferrous metals	0.57%	Oxirane, [[4-(1,1-dimethylethyl)phenoxy]methyl]-	3101-60-8	10.2%
			Silver	7440-22-4	81.3%
			Carbon black	1333-86-4	0.3%
			ALUMINUM(III) HYDROXIDE	21645-51-2	1%
Encapsulation	EP (Epoxy resin)	68.82%	phenolic epoxy resin	61788-97-4	5.7%
			Epoxy resin 89	26335-32-0	6%
			Quartz sand	60676-86-0	87%
Inner preparation	Gold	0.07%	GOLD, ELEMENTAL	7440-57-5	100%
Leadfinish	Tin plating	1.6%	Tin elemental	7440-31-5	100%
			Copper	7440-50-8	0.2%
Leadframe	Nickel and Nickel alloys	28.8%	SILVER, ELEMENTAL	7440-22-4	1.2%
			Iron nickel zinc oxide REACH Article 67 Exemption	12645-50-0	98.6%

## Attached parts list

Part number	Part name
SOT-23/TO-236_Pb&H-free_(H)_Au	Diode/Transistor SMD